

III. CLAIM AMENDMENTS

D2 *sub* 1. (Currently Amended) A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

a plurality of wafer supports connecting joining the first substantially U-shaped plate to the second substantially U-shaped plate; and

more than two retention springs attached to the first substantially U-shaped plate.

2. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a pair of interior arm cutouts.

3. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has a base cutout.

4. (Currently Amended) The semiconductor cassette reducer of claim 1, wherein a base to tip distance of the first substantially U-shaped plate is less than an interior depth of a front opening unified pod to which the

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semiconductor cassette reducer is adapted to be mated.

5. (Original) The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of side panels connected to a pair of arms of the first substantially U-shaped plates.

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6. (Original) The semiconductor cassette reducer of claim 5, wherein the pair of side panels have a plurality of lips.

7. (Original) The semiconductor cassette reducer of claim 1, wherein the first substantially U-shaped plate has an exterior partial 5-shaped cutout,

8. (Original) The semiconductor cassette reducer of claim 1, wherein the plurality of wafer supports includes a pair of columns.

9. (Previously Amended) The semiconductor cassette reducer of claim 8, wherein the pair of columns have at least two positions.

10. (Original) A semiconductor cassette reducer, comprising:

a first substantially U-shaped plate having a first

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pair of arms each having a first arm cutout;

a second substantially U-shaped plate having a second pair of arms each having a second arm cutout;

a plurality of wafer supports connecting the first substantially U-shaped plate to the second substantially U-shaped plate.

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11. (Original) The semiconductor cassette reducer of claim 10, further including a plurality of retention springs attached to the first substantially U-shaped plate.

12. (Original) The semiconductor cassette reducer of claim 11, wherein one of the plurality of retention springs is designed to mate with a lip of a front opening unified pod.

13. (Original) The semiconductor cassette reducer of claim 10, wherein the plurality of wafer supports include a wafer support panel attached to one of the first pair of arms.

14. (Original) A semiconductor cassette reducer comprising:

a first substantially U-shaped plate;

a second substantially U-shaped plate;

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a first wafer support panel attached to a first arm of
the first substantially U-shaped plate and to a first arm
of the second substantially U-shaped plate; and

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a second wafer support panel attached to a second arm
of the first substantially U-shaped plate and to a second
arm of the second substantially U-shaped plate.

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15. (Original) The semiconductor cassette reducer of
claim 14, further including a pair of column wafer supports
attached to a base of the first substantially U-shaped
plate and to a base of the second substantially U-shaped
plate.

16. (Original) The semiconductor cassette reducer of claim
14, wherein the first substantially U-shaped plate has a
plurality of flexible disks.

17. (Original) The semiconductor cassette reducer of
claim 14, wherein the first substantially U-shaped plate
has a pair of arms each having an interior cutout,

18. (Currently Amended) The semiconductor cassette
reducer of claim 14, wherein a base to tip distance of the
first substantially U-shaped plate is less than a diameter
of wafer designed for a front opening unified pod to which
the semiconductor cassette reducer is adapted to be mated.